
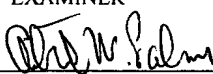


PTO-1449		Application No. unknown		Applicant(s) Scott R. Runnels			
Information Disclosure Citation in an Application		Docket Number 090936.0395		Group Art Unit unknown 2125		Filing Date October 24, 2000	
U.S. PATENT DOCUMENTS							
		DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
QUP	A	5,655,110	08/05/97	Krivokapic et al.	395	500	
QUP	B	5,665,202	09/09/97	Subramanian et al.	438	692	
QUP	C	5,637,031	06/10/97	Chen	541	41	
QUP	D	5,599,423	02/04/97	Parker et al.	156	636.1	
QUP	E	5,526,293	06/11/96	Mozumder et al.	364	578	
QUP	F	5,514,245	05/07/96	Doan et al.	156	636.1	
QUP	G	5,471,403	11/28/95	Fujimaga	364	488	
QUP	H	5,367,465	11/22/94	Tazawa et al.	364	468	
QUP	I	4,833,617	05/23/89	Wang	364	474.15	
	J						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
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NON-PATENT DOCUMENTS							
		DOCUMENT (Including Author, Title, Source, and Pertinent Pages)					DATE
QUP	L	M. Bhusan et al. "Chemical-Mechanical Polishing in Semidirect Contact Mode", J. Electrochem. Soc., Vol. 142, No. 11, pp. 3845-3851					11/95
QUP	M	R. Jairath et al., "Role of Consumables in the Chemical Mechanical Polishing (CMP) of Silicon Oxide Films", SEMATECH Paper					
QUP	N	P. Rentein et al., "Characterization of Mechanical Planarization Processes", VMIC Conference, pp. 57-63					06/90
QUP	O	J. Warnock, "A Two Dimensional Process Model for Chemimechanical Polish Planarization", J. Electrochem. Soc., Vol. 138, No. 8, pp. 2398-2402					08/91
QUP	P	S. Sivaram et al., "Measurement and Modeling of Pattern Sensitivity During Chemical Mechanical Polishing of Interleaved Dielectrics", SEMATECH Paper, Conference Proceedings ULSI-VII, Materials Research Society, pp. 511-517					1992
QUP	Q	S. Runnels, "Advances in Physically Based Erosion Simulators for CMP", J. of Electronic Materials, Vol. 25, No. 10, pp. 1574-1580					1996
QUP	R	M. Ruttan et al., "Pattern Density Effects in Tungsten CMP", Semiconductor International, pp. 123-129					09/95
QUP	S	R. Jairath et al., "Consumables for the Chemical Mechanical Polishing (CMP) of Dielectrics and Conductors", Mat. Res. Soc., Invited Paper					Spring 1994
QUP	T	R. Sivaram et al., "Chemical Mechanical Polishing of Interleaved Dielectrics: Models for Removal Rate and Planarity", Mat. Res. Soc. Smp. Proc. Vol. 260, pp. 53-64					1992
QUP	U	M. Desai et al., "Chemical Mechanical Polishing for Planarization in Manufacturing Environment", Mat. Res. Soc. Symp. Proc. Vol. 337, pp. 99-104					1994
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.							

PTO-1449		Application No. unknown		Applicant(s) Scott R. Runnels			
Information Disclosure Citation in an Application		Docket Number 090936.0395		Group Art Unit unknown 2/2T			
		U.S. PATENT DOCUMENTS					
		DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS	FILING DATE
	A						
	B						
	C						
	D						
	E						
	F						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION YES NO
	G						
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<input checked="" type="checkbox"/>	H	A. Hu et al., "Concurrent Deployment of Run by Run Controller Using SCC Framework", IEEE/SEMI Int'l Semiconductor Manufacturing Science Symp. pp. 126-132					1993
<input checked="" type="checkbox"/>	I	B. Stine et al., "A Closed-From Analytic Model for ILD Thickness Variation in CMP Processes, CMP-MIC Conference, pp. 266-272					1997
<input checked="" type="checkbox"/>	J	V. H. Bulsara et al., "Mechanics of Polishing", Transactions of the ASME, Vol. 65, pp. 410-416					06/98
<input checked="" type="checkbox"/>	K	O.G. Chekina et al., "Wear-Contact Problems and Modeling of Chemical Mechanical Polishing", J. Electrochem. Soc., Vol 145, No. 6, pp. 2100-2106					06/98
<input checked="" type="checkbox"/>	L	H. Kim et al., "The Effect of the Pattern Sensitivity on Interlayer Dielectric Planarization", CMP-MIC Conference, pp. 103-109					1998
<input checked="" type="checkbox"/>	M	W.-T. Tseng et al., "Distribution of Pressure and Its Effects on the Removal Rate During Chemical-Mechanical Polishing Process", CMP-MIC Conference, pp. 87-94					1998
<input checked="" type="checkbox"/>	N	J. Grillaert et al., "Modeling Step Height reduction and Local Removal Rates Based on Pad-Substrate Interactions", CMP-MIC Conference, pp. 79-86					1998
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